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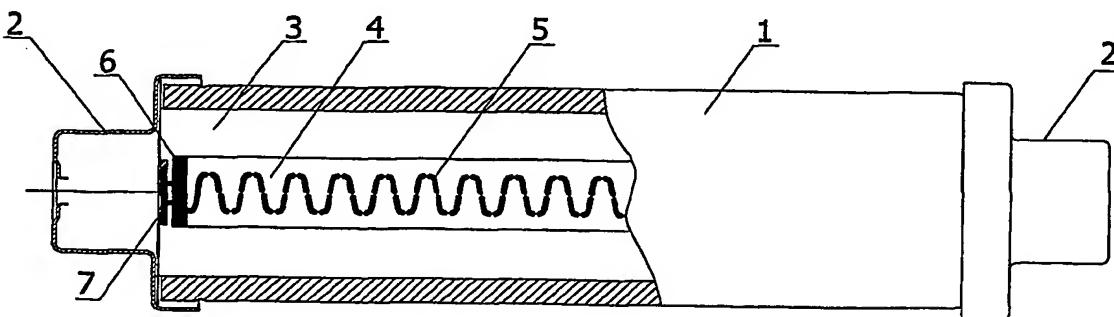
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(54) Title: A HIGH-VOLTAGE THICK-FILM HIGH Rupturing CAPACITY SUBSTRATE FUSE



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(57) Abstract: The subject of the invention is a high-voltage thick-film high rupturing capacity substrate fuse. The characteristic feature of the inventive fuse is that inside a tubular insulating casing /1/, which is closed at both ends with metal endocaps /2/ and filled with arc quenching medium /3/, there is located at least one insulating substrate /4/, along which there is placed at least one fuse element /5/ in the form of a thin conducting film and which has terminal areas /6/ at its ends, which areas are electrically connected with the end-caps by specially shaped contacts /7/ located inside the end-caps. The fuse element comprises a basic part formed by multiple identical V-shaped modules and two end modules forming electric connections between the basic part and the terminal areas. In each module, the arms of the V shape, of a specific width, end with arches directed outwards /8/, which arches are connected with the arches of the arms of the neighboring modules by means of line segments, thus forming a line, which bends many times at a constant angle and has truncated vertices in each module, in which line at least one module contains at least one edge constriction /9/, enabling opening of the current path when the fuse is overloaded.